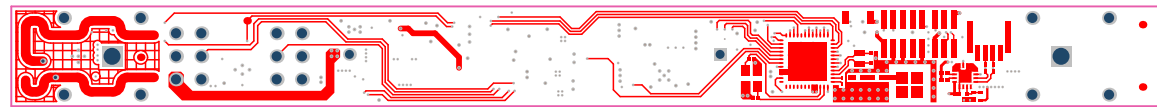
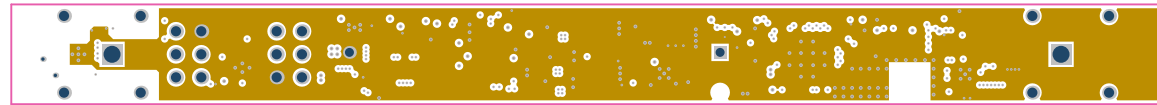




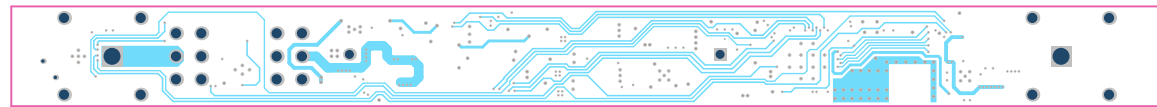
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01014		
PLOT NAME = Top Solder Mask	GENERATED : 3/24/2017 5:22:05 PM	TEXAS INSTRUMENTS	



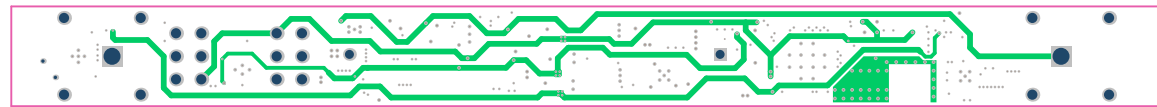
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01014		
PLOT NAME = Top Layer	GENERATED : 3/24/2017 5:22:07 PM	TEXAS INSTRUMENTS	



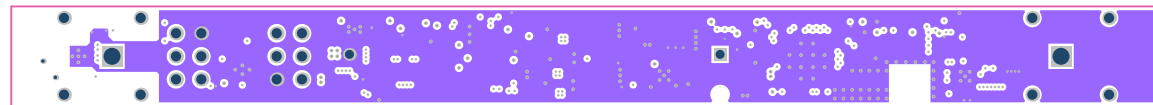
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND	TID #: TIDA-01014		
PLOT NAME = Signal Layer 1	GENERATED : 3/24/2017 5:22:09 PM	TEXAS INSTRUMENTS	



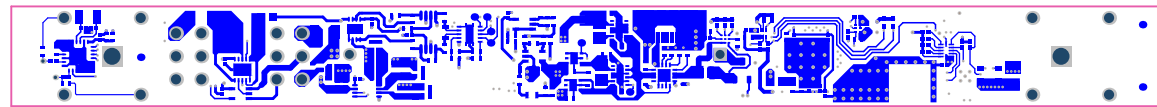
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - Signal	TID #: TIDA-01014		
PLOT NAME = Signal Layer 2	GENERATED : 3/24/2017 5:22:11 PM	TEXAS INSTRUMENTS	



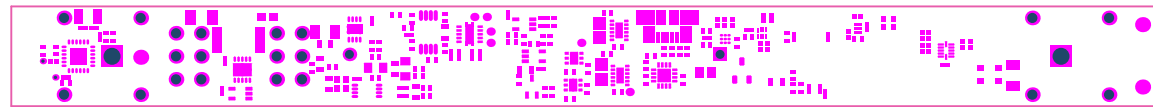
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - PWR	TID #: TIDA-01014		
PLOT NAME = Signal Layer 3	GENERATED : 3/24/2017 5:22:13 PM	TEXAS INSTRUMENTS	



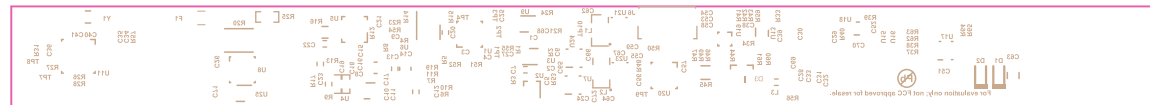
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 5 - GND	TID #: TIDA-01014		
PLOT NAME = Signal Layer 4	GENERATED : 3/24/2017 5:22:14 PM	TEXAS INSTRUMENTS	



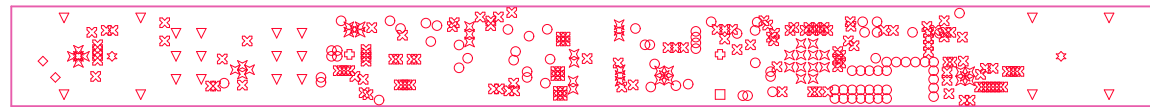
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 6 - Bottom Layer	TID #: TIDA-01014		
PLOT NAME = Bottom Layer	GENERATED : 3/24/2017 5:22:17 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01014		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/24/2017 5:22:19 PM	TEXAS INSTRUMENTS	

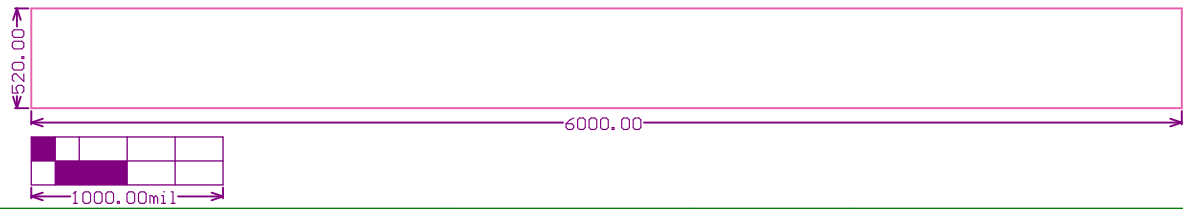


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01014		
PLOT NAME = Bottom Overlay	GENERATED : 3/24/2017 5:22:21 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
□	1	77.95mil (1.980mm)	NPTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊠	137	6.00mil (0.152mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊠	49	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
○	84	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
◇	2	17.72mil (0.450mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊕	2	46.85mil (1.190mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
▽	20	53.15mil (1.350mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
☆	2	88.50mil (2.250mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
	297 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01014		
PLOT NAME = Drill Drawing	GENERATED : 3/24/2017 5:22:23 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01014	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01014		
PLOT NAME = Board Dimensions	GENERATED : 3/24/2017 5:22:25 PM	TEXAS INSTRUMENTS	

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